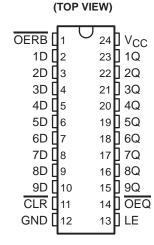
DW OR NT PACKAGE

SDAS028B - APRIL 1984 - REVISED JANUARY 1995

- 3-State I/O-Type Read-Back Inputs
- Bus-Structured Pinout
- True Logic Outputs
- Designed With Nine Bits for Parity Applications
- Package Options Include Plastic Small-Outline (DW) Packages and Standard Plastic (NT) 300-mil DIPs

description

This 9-bit latch is designed specifically for storing the contents of the input data bus and providing the capability of reading back the stored data onto the input data bus. In addition, this device provides a 3-state buffer-type output and is easily implemented in parity applications.

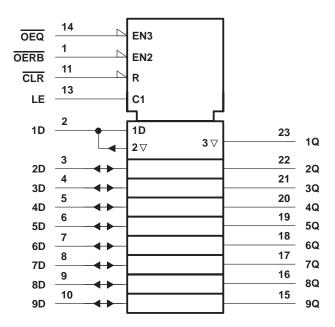


The nine latches are transparent D-type latches. While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. The Q outputs are in the 3-state condition when the output-enable (\overline{OEQ}) input is high.

Read back is provided through the output-enable (OERB) input. When OERB is taken low, the data present at the output of the data latches is allowed to pass back onto the input data bus. When OERB is taken high, the output of the data latches is isolated from the D inputs. OERB does not affect the internal operation of the latches; however, precautions should be taken not to create a bus conflict.

The SN74ALS992 is characterized for operation from 0°C to 70°C.

logic symbol†

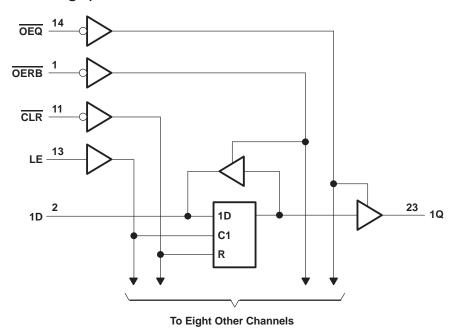


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

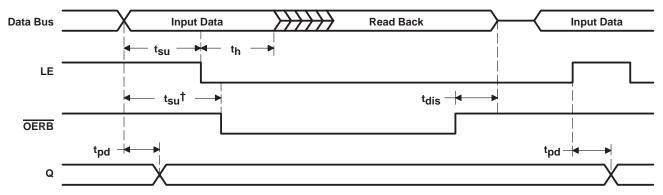


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logic diagram (positive logic)



timing diagram



 $\overline{\text{CLR}} = \text{H}, \overline{\text{OEQ}} = \text{L}$

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

| Supply voltage, V _{CC} | |
|-------------------------------------------------------------|----------------|
| Input voltage, V _I (OERB, OEQ, CLR, and LE) | 7 V |
| Voltage applied to D inputs and to disabled 3-state outputs | 5.5 V |
| Operating free-air temperature range, T _A | 0°C to 70°C |
| Storage temperature range | −65°C to 150°C |

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



[†] This setup time ensures that the read-back circuit will not create a conflict on the input data bus.

recommended operating conditions

| | | | MIN | NOM | MAX | UNIT | |
|-----------------|--------------------------------|-------------------|-----|-----|------|------|--|
| Vcc | Supply voltage | | 4.5 | 5 | 5.5 | V | |
| VIH | High-level input voltage | | 2 | | | V | |
| V _{IL} | Low-level input voltage | | | | 0.8 | V | |
| ЮН | High level output output | Q | | | -2.6 | mA | |
| | High-level output current | D | | | -0.4 | | |
| IOL | Low-level output current | Q | | | 24 | mA | |
| | | D | | | 8 | | |
| t _W | Pulse duration | LE high | 10 | | | ns | |
| | | CLR low | 10 | | | | |
| | Cabinations | Data before LE↓ | 10 | | | | |
| t _{su} | Setup time | Data before OERB↓ | 10 | | | ns | |
| th | Hold time, data after LE↓ | | 5 | | | ns | |
| T _A | Operating free-air temperature | · | 0 | | 70 | °C | |

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| | PARAMETER | MIN T | YP† N | VIAX | UNIT | | | |
|-----------------|---------------------------------------|---------------------------------------------|----------------------------|--------------------|--------------------|------|------|--|
| ٧ _{IK} | | $V_{CC} = 4.5 V,$ | I _I = -18 mA | | - | -1.2 | V | |
| V | All outputs | $V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$ | $I_{OH} = -0.4 \text{ mA}$ | V _{CC} -2 | V _{CC} -2 | | V | |
| VOH | Q | $V_{CC} = 4.5 V,$ | $I_{OH} = -2.6 \text{ mA}$ | 2.4 | 3.2 | | V | |
| | D | V _{CC} = 4.5 V | I _{OL} = 4 mA | (| 0.25 | 0.4 | | |
| \/o. | В | | $I_{OL} = 8 \text{ mA}$ | (| 0.35 | 0.5 | ٧ | |
| VOL | | V 45V | I _{OL} = 12 mA | (| 0.25 | 0.4 | | |
| | Q | V _{CC} = 4.5 V | $I_{OL} = 24 \text{ mA}$ | (| 0.35 | 0.5 | | |
| lozh | Q | $V_{CC} = 5.5 V,$ | $V_0 = 2.7 \text{ V}$ | | | 20 | μΑ | |
| lozL | Q | $V_{CC} = 5.5 V,$ | V _O = 0.4 V | | | -20 | μΑ | |
| 1 ₁ | D inputs | V 55V | V _I = 5.5 V | | | 0.1 | mA | |
| | All others | V _{CC} = 5.5 V | V _I = 7 V | | | 0.1 | IIIA | |
| . D inputs‡ | | V F V | V-27V | | | 20 | | |
| lн | All others | V _{CC} = 5.5 V, | $V_{I} = 2.7 \text{ V}$ | | | 20 | μΑ | |
| | D inputs‡ | V 55V | V ₁ 0.4 V | | - | -0.1 | | |
| IIL. | All others | V _{CC} = 5.5 V, | $V_{I} = 0.4 V$ | | - | -0.1 | mA | |
| IO§ | | V _{CC} = 5.5 V, | V _O = 2.25 V | -30 | - | -112 | mA | |
| | | | | | 30 | 50 | | |
| ICC | V _{CC} = 5.5 V, OERB high | | Outputs low | | 50 | 80 | mA | |
| | | | Outputs disabled | | 35 | 55 | | |



[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. ‡ For I/O ports (Q_A thru Q_H), the parameters I_{IH} and I_{IL} include the off-state output current. § The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

SN74ALS992 9-BIT D-TYPE TRANSPARENT READ-BACK LATCH WITH 3-STATE OUTPUTS SDAS028B – APRIL 1984 – REVISED JANUARY 1995

switching characteristics (see Figure 1)

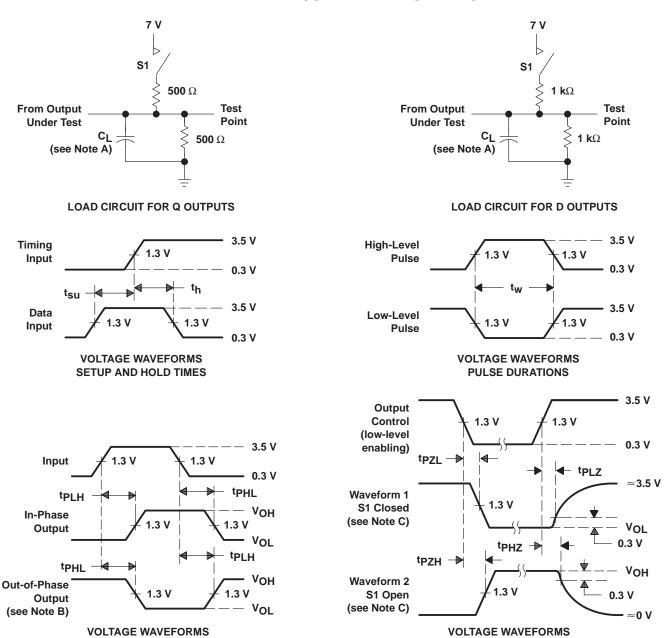
| PARAMETER | FROM (INPUT) | TO (OUTPUT) | V _{CC} = 4.5 C _L = 50 pF T _A = MIN to | UNIT | |
|--------------------|--------------------------------|----------------|----------------------------------------------------------------------------|------|-----|
| | | | MIN | MAX | |
| ^t PLH | D | | 3 | 14 | |
| ^t PHL | ט | Q | 4 | 16 | ns |
| ^t PLH | LE | | 6 | 20 | ns |
| ^t PHL | LL | Q | 8 | 25 | 119 |
| 4 | | Q | 6 | 20 | |
| ^t PHL | CLR | D | 8 | 26 | ns |
| t _{en} ‡ | | _ | 4 | 21 | |
| t _{dis} § | OERB | D | 2 | 14 | ns |
| t _{en} ‡ | O EQ | 0 | 4 | 18 | |
| t _{dis} § | OEQ | Q | 1 | 14 | ns |

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡]t_{en} = t_{PZH} or t_{PZL} §t_{dis} = t_{PHZ} or t_{PLZ}

ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

PROPAGATION DELAY TIMES

- B. When measuring propagation delay times of 3-state outputs, switch S1 is open.
- C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- D. All input pulses have the following characteristics: $PRR \le 1$ MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.

Figure 1. Load Circuits and Voltage Waveforms



PACKAGE OPTION ADDENDUM

www.ti.com 11-Nov-2009

PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | e Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|-----------------|--------------------|------|----------------|---------------------------|------------------|------------------------------|
| SN74ALS992DW | ACTIVE | SOIC | DW | 24 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74ALS992DWG4 | ACTIVE | SOIC | DW | 24 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74ALS992NT | ACTIVE | PDIP | NT | 24 | 15 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74ALS992NTE4 | ACTIVE | PDIP | NT | 24 | 15 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

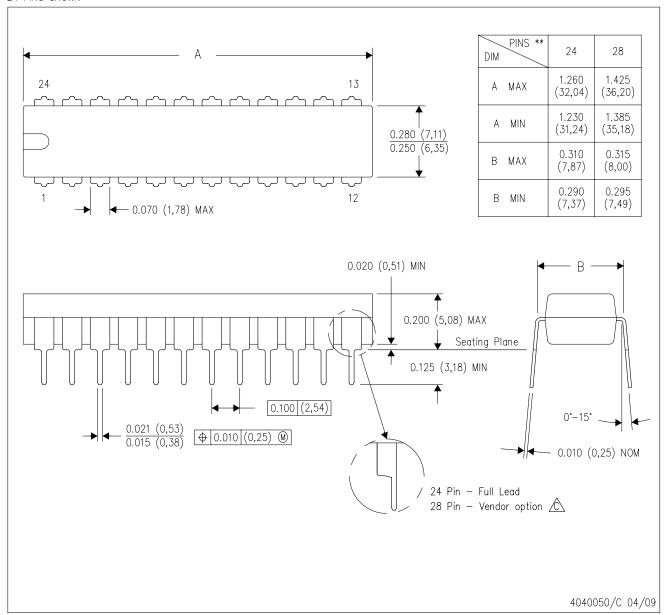
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NT (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

24 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

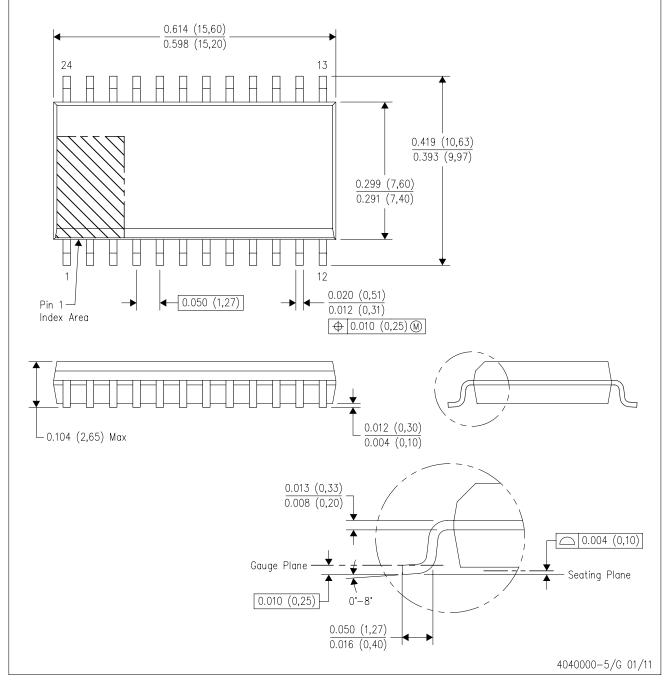
B. This drawing is subject to change without notice.

The 28 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



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